



Material Content Data Sheet



Sales Product Name		BSZ065N03LS		Issued		24. January 2018		
MA#		MA001646240						
Package		PG-TSDSON-8-25		Weight*		35.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.194	0.55	0.55	5498	5498
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		70	
	non noble metal	zinc	7440-66-6	0.010	0.03		279	
	non noble metal	iron	7439-89-6	0.197	0.56		5572	
wire	non noble metal	copper	7440-50-8	7.988	22.63	23.23	226265	232186
	noble metal	gold	7440-57-5	0.036	0.10	0.10	1029	1029
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1086
encapsulation	plastics	epoxy resin	-	1.975	5.59		55948	
	inorganic material	silicondioxide	60676-86-0	17.164	48.61	54.31	486153	543187
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11196	11196
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	575	575
solder	non noble metal	tin	7440-31-5	0.007	0.02		188	
	noble metal	silver	7440-22-4	0.008	0.02		235	
	non noble metal	lead	7439-92-1	0.317	0.90	0.94	8986	9409
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2662	
	non noble metal	copper	7440-50-8	3.816	10.81	11.09	108083	110911
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2064	
	non noble metal	copper	7440-50-8	2.959	8.38	8.60	83816	86009
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com